

Title: Photonics packaging and assembly for quantum applications

Abstract:

The packaging and assembly of photonic integrated circuits (PICs) is an important critical success factor in the product development of PIC based products. Successful PIC packaging require optical interfacing, electrical interfacing, thermal management, mechanical stability and compatibility with the environmental requirements. Several state of the art processes are available from the semiconductor IC packaging industry but a few key processes are very specific for PIC packaging.

PHIX is offering packaging and assembly services to customers who are developing PIC based products and is servicing many customers in a broad range of applications including several quantum applications which require some specific specifications. In this presentation, the challenges of PIC packaging will be addressed and the specific challenges for quantum applications will be highlighted.

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